



RHBS802 - RHBS810

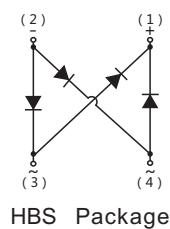
8A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

Features

- Surface mount bridge, small package;
- Ideal for printed circuit boards;
- Glass passivated chip junction;
- High forward current capability up to 8.0A;
- High surge current capability;
- High heat dissipation capability;
- Low profile package;
- Low forward voltage drop;
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0;

Mechanical Data

- Case: HBS;
Epoxy meets UL-94V-0 Flammability rating;
- Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102;
- High temperature soldering guaranteed:
Solder Reflow 260°C, 10seconds;
- Polarity: As marked on body;
- Marking: Type number;



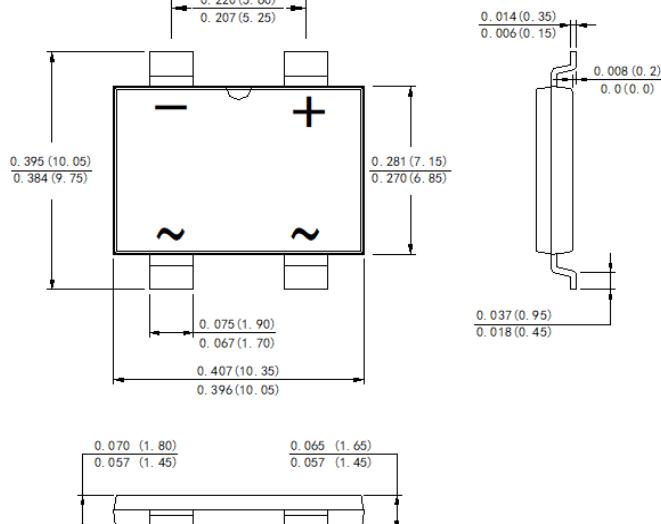
VOLTAGE RANGE

200 to 1000 Volts

CURRENT

8.0 Amperes

HBS



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

| Parameter | Symbols | RHBS802 | RHBS804 | RHBS806 | RHBS808 | RHBS810 | Units |
|--|-------------------------------------|---------|---------|---------|----------------------|---------|--------------------|
| Maximum Repetitive Peak Reverse Voltage | V_{RRM} | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS voltage | V_{RMS} | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | V_{DC} | 200 | 400 | 600 | 800 | 1000 | V |
| Average Rectified Output Current | I_o | | | | 8.0 | | A |
| Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method) | I_{FSM} | | | | 200 | | A |
| I^2t Rating for Fusing | I^2t | | | | 166 | | A^2S |
| Maximum Forward Voltage at 1.0 A | V_F | | | | 0.83 (max.) | | V |
| Maximum Forward Voltage at 8.0 A | V_F | | | | 1.3 | | V |
| Maximum DC Reverse Current @ $T_A=25\text{ }^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A=125\text{ }^\circ\text{C}$ | I_R | | | | 0.20 100 | | μA |
| Maximum reverse recovery time ($I_F=0.5\text{A}, I_{R}=1.0\text{A}, I_{rr}=0.25\text{A}$) | T_{rr} | | 150 | 250 | 500 | | nS |
| Typical Junction Capacitance (Note1) | C_J | | | | 48 | | pF |
| Typical Thermal Resistance (Note2) | R_{BJA} R_{BJC} R_{BLJ} | | | | 70.0 15.0 22.0 | | $^\circ\text{C/W}$ |
| Operating and Storage Temperature Range | T_j, T_{stg} | | | | -55 ~ +150 | | $^\circ\text{C}$ |

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with $4 \times 1.5'' \times 1.5''$ (3.81x3.81 cm) copper pad.

RATING AND CHARACTERISTIC CURVES (RHBS802 THRU RHBS810)

FIG.1 Derating Curve Output Rectified Current

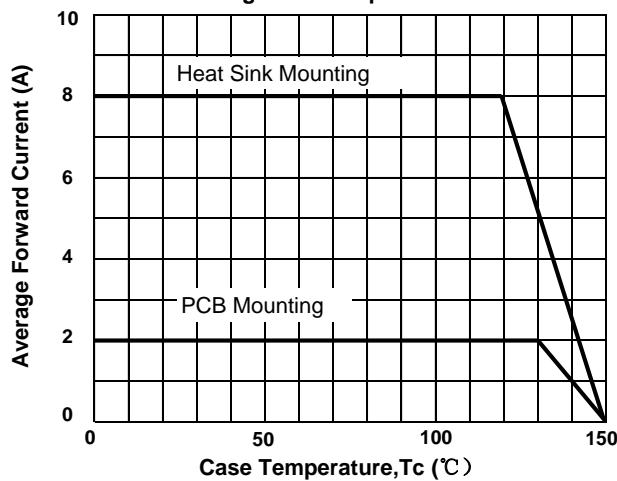


FIG.2 Typical Forward Characteristics per Diode

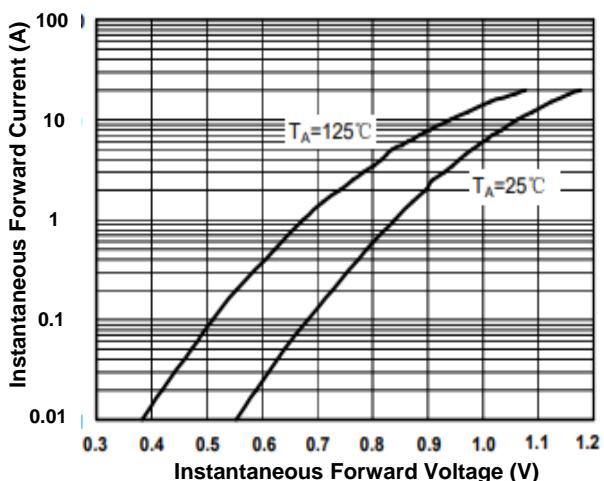


FIG.3 Maximum Non-Repetitive Peak Forward Surge Current per Diode

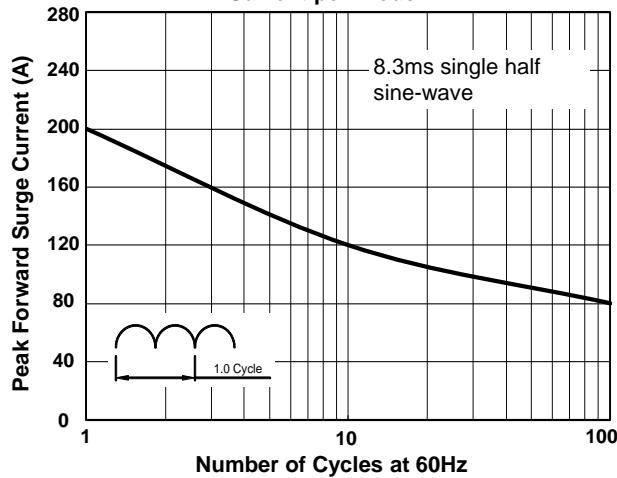


FIG.4 Typical Reverse Characteristics per Diode

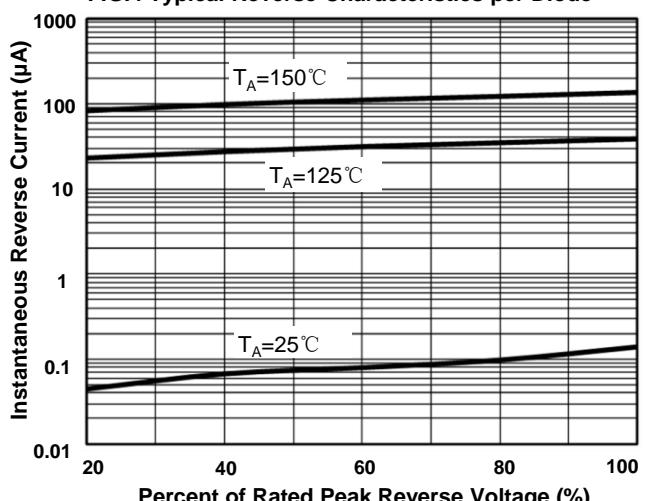
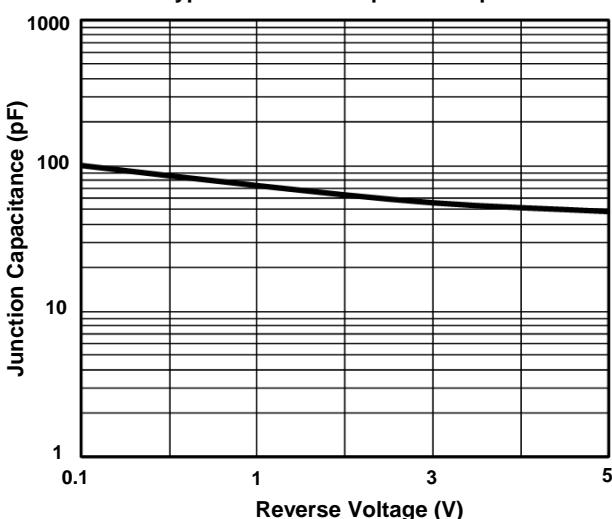


FIG.5 Typical Junction Capacitance per Diode



Suggested PCB printfoot layout

Unit: inches (mm)

